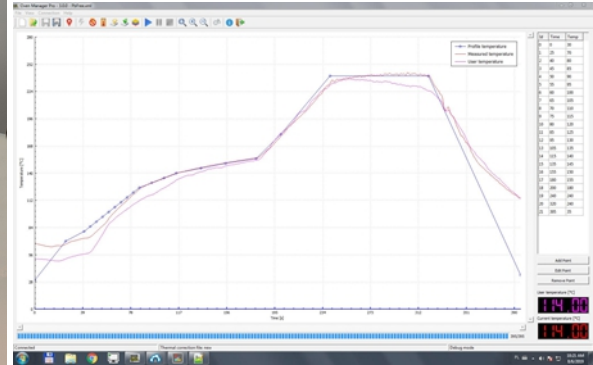


# Reflow oven RK 360



## Reflow oven RK 360

### Technical data

#### Infrared + Air circulation + Air cooling, Pb-free Reflow Oven

Surface mounting of units on boards require the exposure of the device package to high temperature to melt the lead finish for board soldering. A lot of the alternative "lead-free" solder materials being considered for use in IC assembly today require a peak soldering temperature of about 250 to 260 deg C, versus the peak temperature of 230 to 235 deg C for Sn-Pb solder. This means that lead-free IC's will need a higher temperature for board mounting, and will therefore be subjected to more severe thermo-mechanical stresses during the process.

This Oven feature a complete system for today's solder/ Pb-Free solder(260C) requirement. The computer control system for free programmable temperature curve. High power heating element with force air heating method provide a very even soldiering hot zone across the total soldiering area, This cost effective unit offer high production count ( 4~5 mins per cycle of 360mm x 360mm board) which ideal for low to medium size of SMD production. The static soldering process offer very stable non moving especially important for fine pitch SMD soldering.

#### Features:

- Infrared Array + Force Air ( high volume, low pressure ) Heating Method.
- Free programmable control for temperature curve setting.
- Internal cooling fan for fast Cool down performance.
- Fully Automatic, fully static ( non moving rail) operation, single or double side board soldering.
- Large transparent glass window see through the soldering process with high temperature
- Internal complete high gloss stainless steel construction, high IR efficiency and easy to clean, maintenance.
- Ball bearing Rail draw system for stable solder board exchange with minimum vibration.
- Top Open design for quick access to heating element and service.
- Dual channel air circulation for fast cool down process - exhaust port will be automatically open
- Software for graphical interface mode – Ethernet and USB Interface for external PC

#### Specifications:

- Maximum heating area: 460mm x 410mm
- Free programable in graphical mode
- 6 thermocouples inside heating chamber
- 1 interface for additional thermocouple – direct measurement on the PCB
- Fume extractor interface – diameter 80mm
- Maximum Temperature: 290 °C
- Operation environment: 0-40 °C
- Maximum power consumption: 3500 W / 1000 W Typ.
- Power supply: AC 230V / 50-60Hz
- Weight: 55kg
- Dimension: 675 x 630 x 300 mm